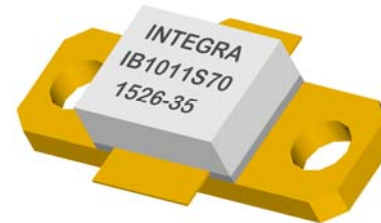


## L-Band Avionics Transistor

The high power pulsed avionics transistor device part number IB1011S70 is designed for L-Band radar systems operating between 1030 and 1090MHz. While operating in class C mode this common base device supplies a minimum of 70 watts of peak pulse power under the conditions of 8W input power, and 10µs pulse width, 1% duty cycle. All devices are 100% screened for large signal RF parameters.



### Silicon Bipolar

- Ultra-high  $f_T$

### Class C Operation

- High Efficiency

### Common Base Configuration

- Single Power Supply

### Gold Metal

- Maximum Reliability

### Emitter Ballasting

- Optimum Thermal Distribution

### Internal Impedance Matching

- Ease of Use
- Ultra-low Loss Design

### BeO Package

- Unmatched Thermal Reliability

### RF Test Fixture

- Broadband
- Matched to 50Ω
- Long-term Correlation
- 100% Device RF Screening
- No External Tuning Allowed
- Micro-strip structure on soft pc board with dielectric constant 10.2

*TYPICAL DATA    TYPICAL DATA    TYPICAL DATA    TYPICAL DATA*

Device	Freq (MHz)	Vcc (V)	Pin (W)	IRL (dB)	Pout (W)	Gp (dB)	Ic (A)	Nc (%)	Droop (dB)	VSWR	
										2   1	3   1
D1790-1	1030	50	8	22	87.8	10.4	2.5	70	-0.1	s	p
D1790-4	1030	50	8	21	86.6	10.3	2.3	75	-0.1	s	p

Pulse width = 10 us

Duty Cycle = 1 %

s = stable, p = passed

**MAXIMUM RATINGS**

Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
BD	Collector-Emitter Voltage	$V_{CES}$	--	65	V	$V_{BE}=0V$ .
BD	Emitter-Base Voltage	$V_{EBO}$	--	2	V	--
BD	Storage Temperature Range	$T_{STG}$	-65	+150	°C	--
BD	Operating Junction Temperature Range	$T_J$	--	+200	°C	--
Note	Screen 'BD' = parameter qualified By Design.					

**THERMAL CHARACTERISTICS**

Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
BD	Thermal Resistance	$R_{TH(JC)}$	--	0.26	°C/W	$V_{CC}=V1$ , $PW=PW1$ , $DF=DF1$ , $T_F=25\pm5^\circ C$ , $P_{in} = 8W$ .
Note	Screen 'BD' = parameter qualified By Design.					

**PROCESSING SPECIFICATIONS**

Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
100%	DC Wafer Probe	--	--	--	--	Per Integra specification.
Q1	Wafer DC and RF Qualification	--	--	--	--	Per Integra specification.
LM	Wire Bond Strength	--	--	--	--	Line monitor per Integra specification.
100%	Pre-cap visual inspection	--	--	--	--	Per Integra specification.
100%	Gross leak test	--	--	--	--	MIL-STD-750D, Method 1071.6, Test Condition C.
Note	Screen 'Q1' = parameter is qualified by assembly and test of 3 pieces minimum per wafer.					
Note	Screen 'LM' = parameter is qualified by assembly line monitor.					

**DC ELECTRICAL CHARACTERISTICS**

Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
100%	Collector-Emitter Breakdown Voltage	$BV_{CES}$	65	--	V	$I_C=15mA$ , $V_{BE}=0V$ , $T_F=25\pm5^\circ C$ .
100%	Zero Base Voltage Collector Leakage Current	$I_{CES}$	--	100	uA	$V_{CE}=50V$ , $V_{BE}=0V$ , $T_F=25\pm5^\circ C$ .
100%	DC Current Gain	$H_{FE}$	5	100	--	$V_{CE}=5V$ , $I_C=0.1A$ , $T_F=25\pm5^\circ C$ .

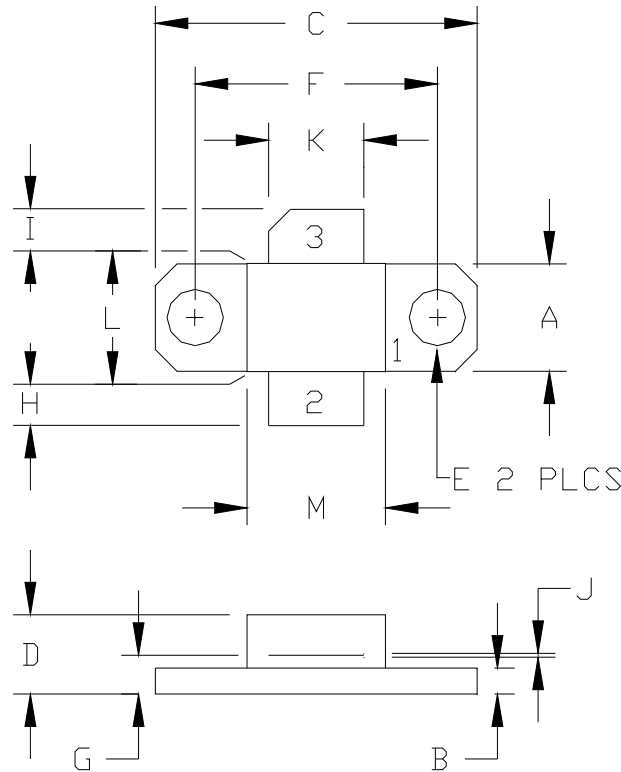
**RF ELECTRICAL CHARACTERISTICS**

Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
100%	Input Return Loss	IRL	10	--	dB	$V_{CC}=V1, PW=PW1, DF=DF1, T_F=25\pm5^\circ C, P_{IN}=P_{IN1}, F=F1.$
100%	Output Power	$P_{out}$	70	--	W	$V_{CC}=V1, PW=PW1, DF=DF1, T_F=25\pm5^\circ C, P_{IN}=P_{IN1}, F=F1.$
100%	Power Gain	Gp	9.4	--	dB	$V_{CC}=V1, PW=PW1, DF=DF1, T_F=25\pm5^\circ C, P_{IN}=P_{IN1}, F=F1.$
100%	Collector Efficiency ( $P_o/I_c/V_{CC}$ )	$N_c$	55	--	%	$V_{CC}=V1, PW=PW1, DF=DF1, T_F=25\pm5^\circ C, P_{IN}=P_{IN1}, F=F1.$
100%	Pulse Amplitude Droop	D	--	0.5	dB	$V_{CC}=V1, PW=PW1, DF=DF1, T_F=25\pm5^\circ C, P_{IN}=P_{IN1}, F=F1.$
--	--	--	--	--	--	--
100%	Stability into 1.5:1 VSWR.	VSWR-S	--	--	--	Rotate 1.5:1 output VSWR through 360° phase. No oscillatory or pulse break-up characteristics allowed on detected output pulse. All non-harmonically related signals must be at least -65 dBc.
100%	3:1 Load Mismatch Tolerance	LMT	--	--	--	$V_{CC}=V1, PW=PW1, DF=DF1, T_F=25\pm5^\circ C, P_{IN}=P_{IN1}, F=F1.$ Rotate 3:1 output VSWR through 360° phase.
Note	V1 = 50V; PW1 = 10µs; DF1 = 1%; P <sub>IN1</sub> = 8W; F1 = 1030 MHz.					
Note	T <sub>F</sub> = Device flange temperature.					
Note	Screen 'BD' = parameter qualified By Design.					

**RF TEST FIXTURE IMPEDANCE CHARACTERISTICS**

Frequency (MHz)	$Z_{IF}$ ( $\Omega$ )	$Z_{OF}$ ( $\Omega$ )
1030	4-j3	3.8+j5.5
Impedance Definition		

**PACKAGE DIMENSIONAL OUTLINE DRAWING**



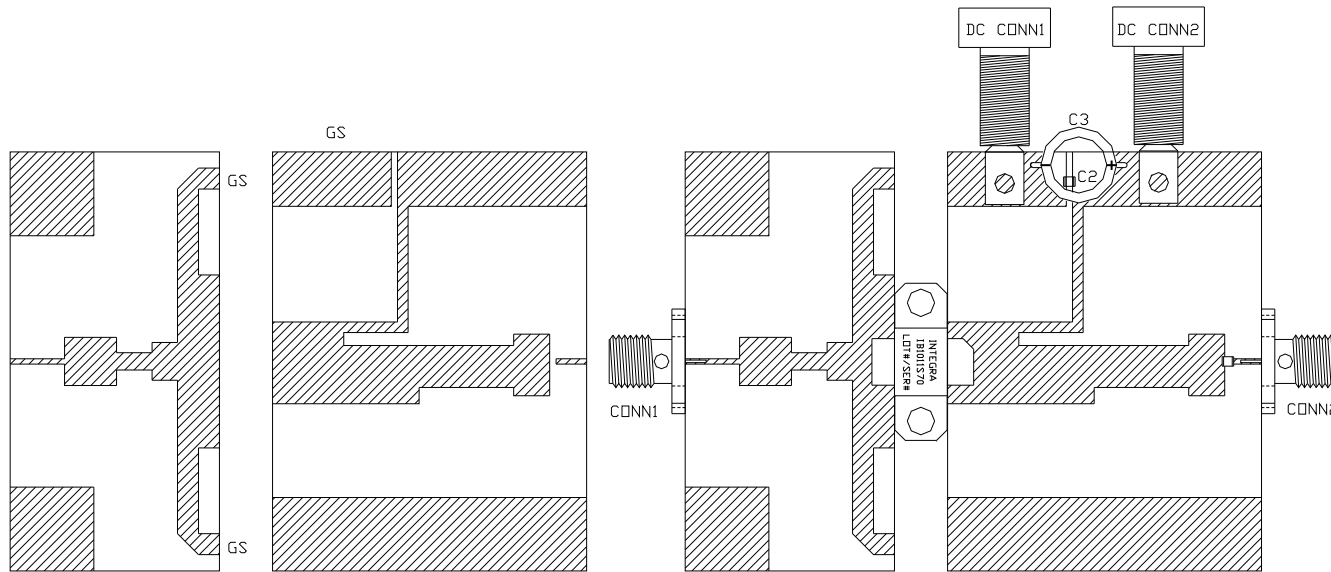
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.243	0.253	6.17	6.43
B	0.055	0.065	1.40	1.65
C	0.739	0.749	18.77	19.02
D	0.178	0.188	4.52	4.78
E	0.125	0.135	3.18	3.43
F	0.555	0.565	14.10	14.35
G	0.082	0.092	2.08	2.34
H	0.080	0.150	2.79	3.56
I	0.080	0.150	2.03	2.54
J	0.004	0.006	0.10	0.15
K	0.215	0.225	5.46	5.72
L	0.245	0.255	6.22	6.48
M	0.315	0.325	8.00	8.26

PIN SCHEDULE	
1	BASE
2	EMITTER
3	COLLECTOR

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DOCUMENT NUMBER: IB1011S70	REV: NC
SHEET NAME: 06-OUTLINE	REV: NC

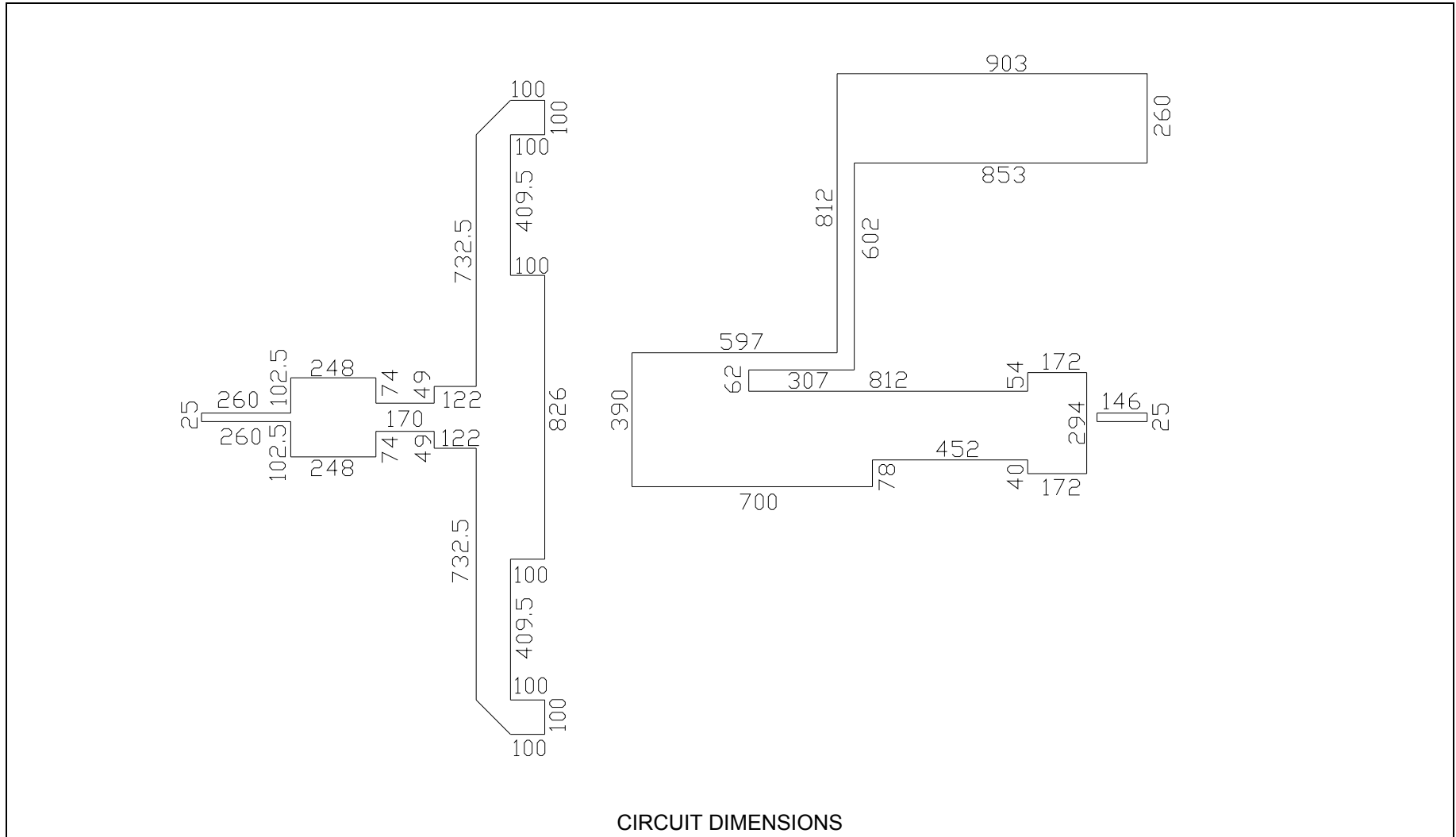
**RF TEST FIXTURE**



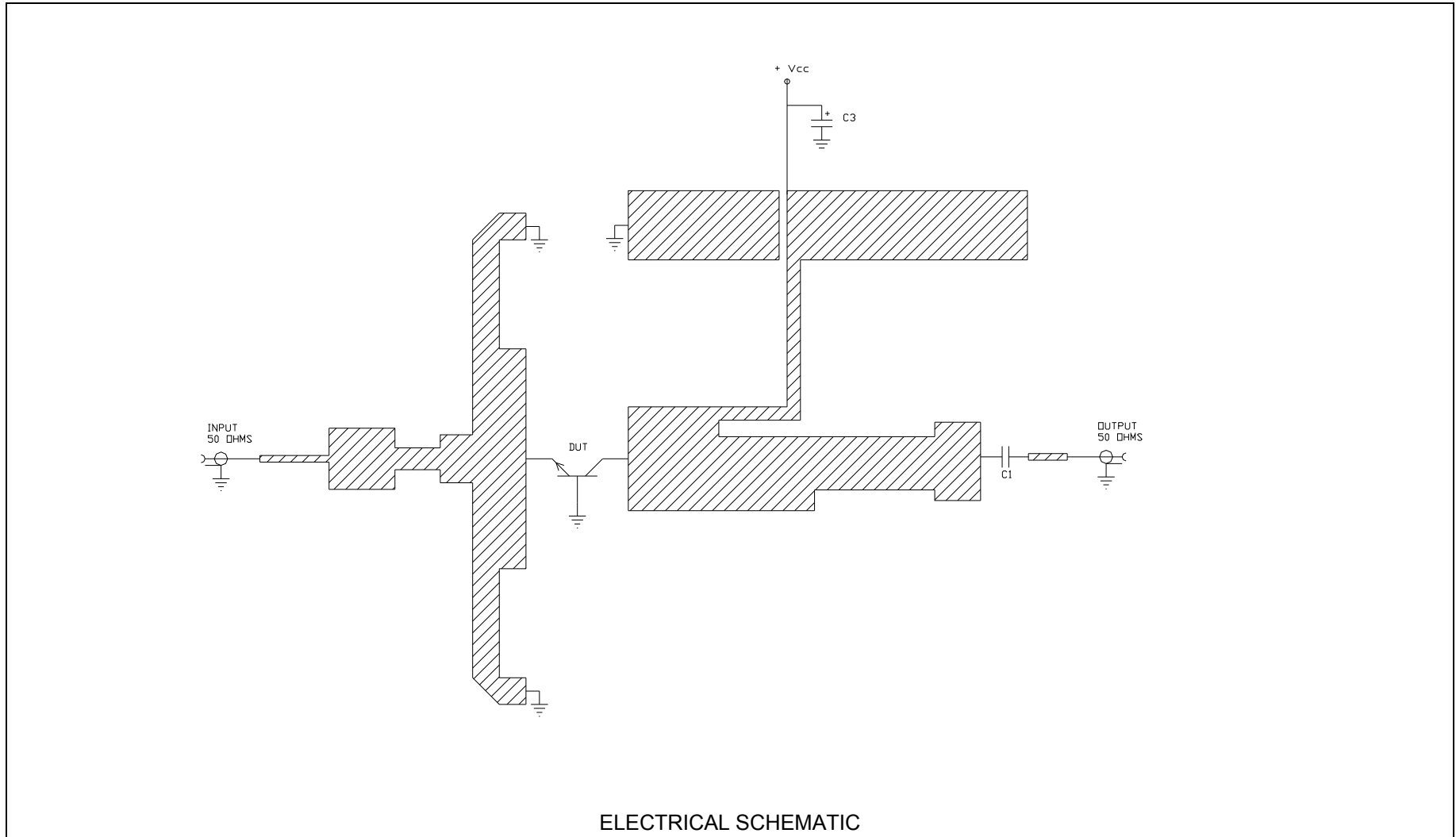
COMPONENT	DESCRIPTION
DUT	TRANSISTOR #IB1011S70, MOUNT HARD TO THE RIGHT
PC BOARD	ROGERS #R03010, TH=0.025"
C1, C2	CHIP CAPACITOR, TYPE ATC100A, 100 pF
C3	ELECTROLYTIC CAPACITOR, 68uF / 63V
GS	GROUND SHIM, COPPER, TH=0.001"
CONN1, CONN2	SMA CONNECTOR, TYPE QS #2052-5636-02
INPUT PC BOARD CARRIER	2 INCH BRASS - 03
OUTPUT PC BOARD CARRIER	2 INCH BRASS - 05
TRANSISTOR CARRIER	2 INCH COPPER - 01
TRANSISTOR CLAMP	NORYL CLAMP - 01
HEATSINK	2 INCH HEATSINK - 11
DC CONN1	BANANA JACK, BLACK
DC CONN2	BANANA JACK, RED
NOTE	FIXTURE HARDWARE DRAWINGS AVAILABLE ON REQUEST

**ASSEMBLY AND PARTS LIST**

**RF TEST FIXTURE**



**RF TEST FIXTURE**



**DEFINITIONS**

<b>Data Sheet Status</b>	
Proposed Specification	This data sheet contains proposed specifications.
Preliminary Specification	This data sheet contains specifications based on preliminary measurements and data.
Product Specification	This data sheet contains final product specifications.
<b>Maximum Ratings</b>	
Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only. Operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.	

**WARNING**

<b>Product and environmental safety - toxic materials</b>
This product contains beryllium oxide. The product is entirely safe provided that the BeO base is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with general or domestic waste.

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